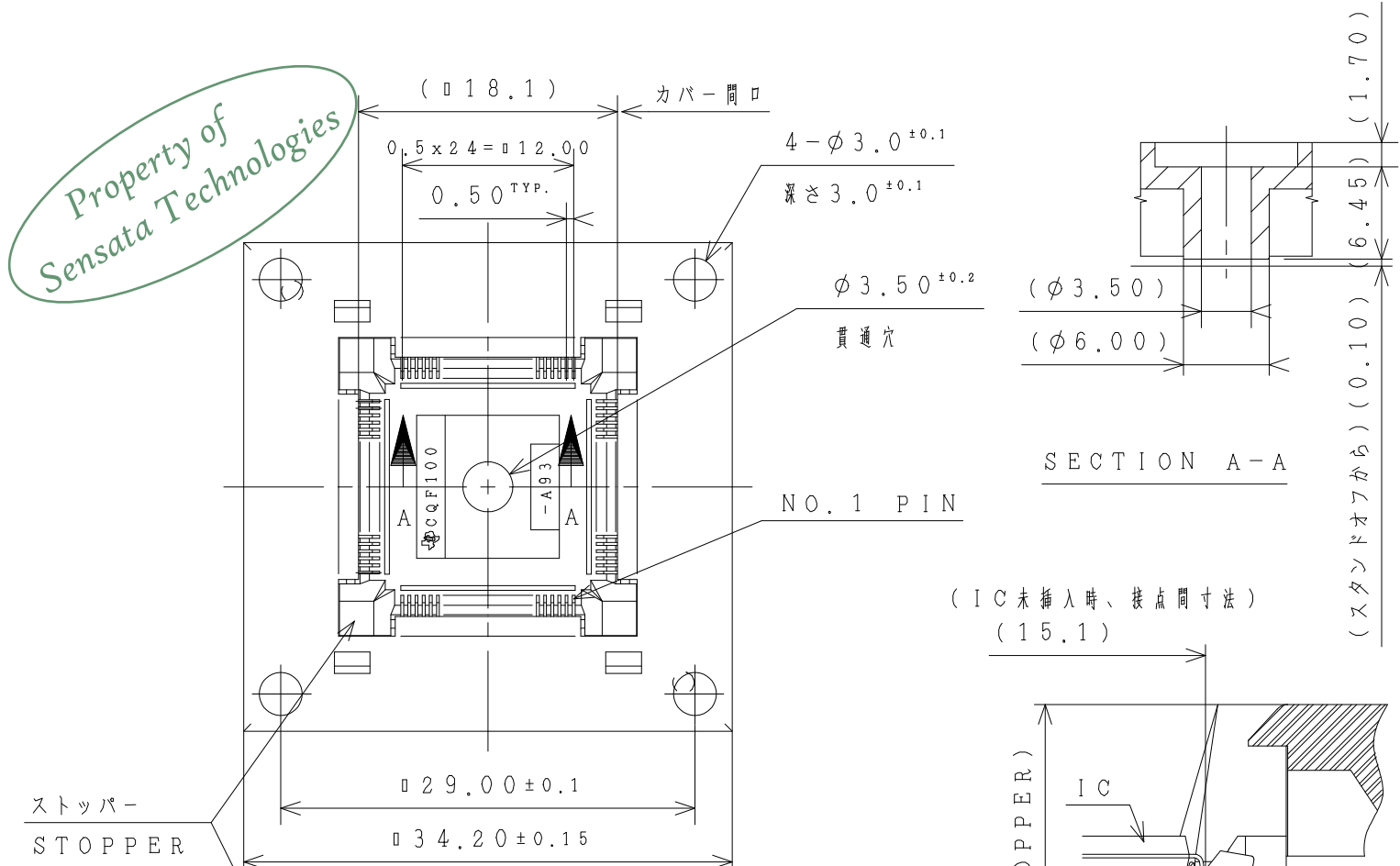
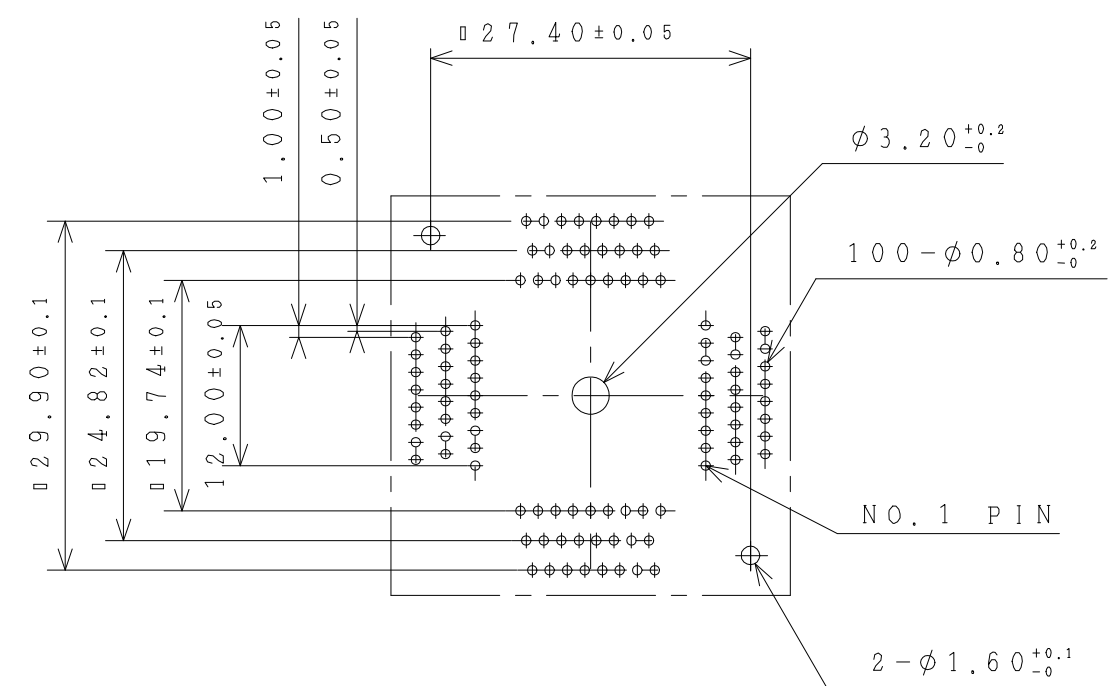
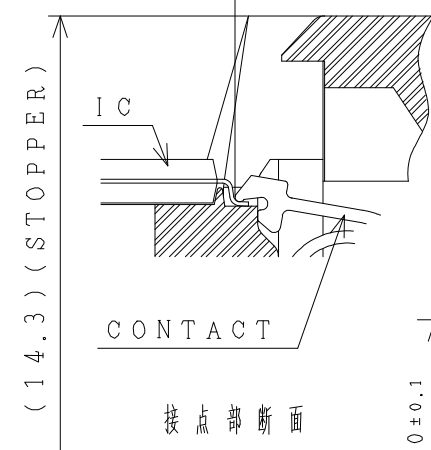


Property of
Sensata Technologies

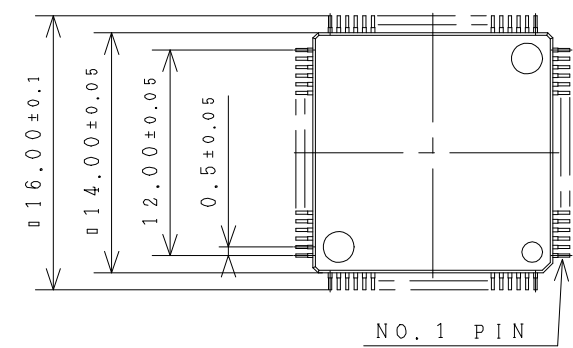
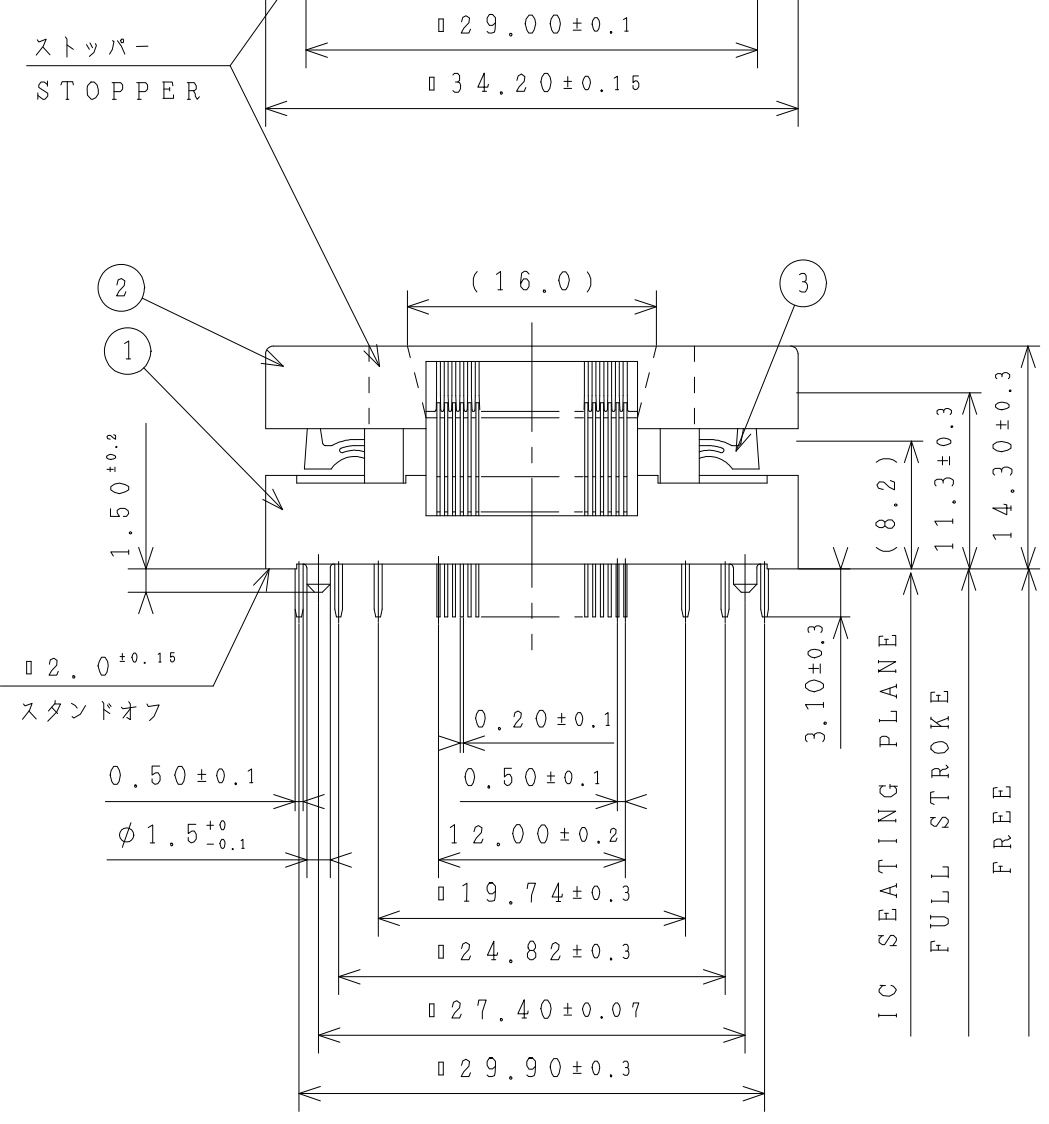


SECTION A-A

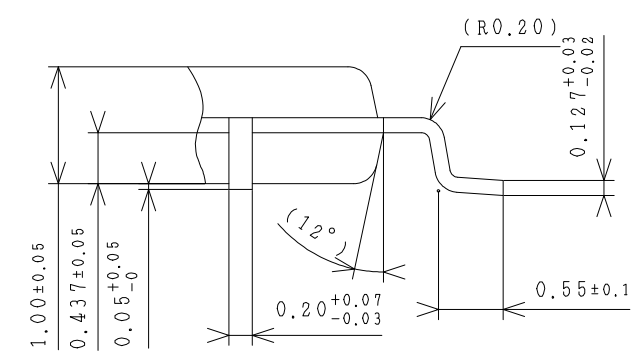
(IC未挿入時、接点間寸法)
(15.1)



PCB HOLE (TOP VIEW)



適合IC寸法



3	CONTACT	COPPER ALLOY	100	GOLD PLATE
2	COVER	PEI (テフロン入り)	1	UL94V-0
1	BASE	PEI	1	UL94V-0
NO	PART DESC	MATERIAL	QTY	NOTE

△D						
△C						
△B						
A	INITIAL RELEASE (ECNP-157)					
REV	DESCRIPTION	DRA.	DES.	CHE.	ENG.	APP.
TEXAS INSTRUMENTS KOREA LIMITED JINCHEON PLANT						
TITLE QFP(FP) BURN IN TEST SOCKET			PART DESC. 80pin 0.5pitch SALES DRAWING			
DRAWING NUMBER CQF100-A93					REV. A	SCALE χ